

February 10, 2003

NEWS AND ANNOUNCEMENTS

World Economic Forum Names Pamela Lipson, Inventor of Key Teradyne Inspection Technology, as 2002 "Technology Pioneer" – Groundbreaking Image-Analysis Technology Puts Teradyne Machine Vision on Leading-Edge

Dr. Pamela Lipson and her company, Imagen, have been recognized as one of an elite group of 40 "Technology Pioneers for 2003" by the World Economic Forum in Geneva, Switzerland. Lipson and Imagen were recognized for the development of innovative technologies for recognition and analysis of complex visual and image-based information. To read more about Teradyne's use of this innovative technology in its soon to be introduced Optima™ 7200 OPT machine vision system, click here: http://www.teradyne.com/prods/cbt/news/newsdesk/70news_pr_030127.html

Teradyne and Marconi Selenia Communications Complete Digital Test Unit Integration for Military/Aerospace Programs

Teradyne's powerful and flexible M910 Digital Test Instrument (DTI) has been integrated into the Marconi Selenia Communications general purpose automatic test equipment (GPATE) platform as part of their project to develop test engineering support for military/aerospace programs including the Typhoon and Tornado fighter jets and NH90 Helicopter. To read more about this project and Teradyne's involvement, click here: http://www.teradyne.com/prods/cbt/news/newsdesk/71news_pr_030204.html

Product Press Releases – Web Access – * New Feature *****

To make it more convenient for you to access press releases specific to product announcements, we have added a new feature to Teradyne's Assembly Test Division (ATD) web site. You will now be able to read applicable press releases under each product heading. Simply click on the product family on the ATD home page and then select the product type. A new heading for Press Releases will be visible following the individual list of product offerings. Click here to access the ATD home page: <http://www.teradyne.com/prods/cbt/cbthome.html>

UPCOMING EVENTS

Apex 2003 – Anaheim, CA – March 31-April 2, 2003 - Visit Teradyne at Booth #2050

Learn more about new advancements in the assembly test areas as Teradyne presents three technical presentations at this year's event.

- *Management Processes for DPMO Metrics Reduce the Cost of PCB Assembly* by Amit Verma
- *Psycho-Physical Artifact Modeling Makes for Smarter Machine Vision Technology* by John Arena
- *Flexible Rules Based Thermal Profiling for Rework* by Don Naugler

For more information about the content of these papers and the dates/times of the presentations, click here:

<http://www.teradyne.com/prods/cbt/news/tradeshows/03apex.html>

Teradyne Users' Group (TUG), Nashville, TN – May 5-7, 2003

The planning stage of the Teradyne Users' Group 2003 Conference is complete. Abstracts have been accepted, and a technical program has been developed. To preview the complete program, click here: <http://www.teradyne.com/prods/tug/t2003proghome.html>

To access abstracts for the Board Test: Mil/Aero Functional Test Program, click here: <http://www.teradyne.com/prods/tug/t2003mftprog.html>

To access abstracts for the Board Test: Commercial Manufacturing Test Program, click here: <http://www.teradyne.com/prods/tug/t2003mptprog.html>

RECENT TECHNICAL PAPERS, ARTICLES, & PUBLICATION

"Effective Test Strategies for Modern Printed Circuit Assemblies" by Amit Verma (*Electronics Engineering Times [EET] China, August 2002*)

Electronics manufacturers have a multitude of issues to consider when designing test strategies for their PCBAs. Increasing time-to-market pressures mandate that test strategies are optimized early in PCB design, before manufacture. This article investigates the need for distributed test solutions and explains how design for test (DFT) software can be used to optimize test strategies during PCB design. Click here for the Chinese version of this article as published in EET China:

http://www.teradyne.com/prods/cbt/products/library/xray/effective_test_pcba_0208.pdf

Click here for the English version of the above article:

http://www.teradyne.com/prods/cbt/products/library/xray/effective_test_pcba_0208_english.pdf

"Optimising Test Where ICT Access is Limited" by Amit Verma (*Printed Circuit Europe – 4th Quarter 2002*)

Electronics manufacturers have a multitude of issues to consider when designing process test strategies for their PCBAs; a variety of tools including automated optical inspection (AOI), automated x-ray inspection (AXI), flying probe test (FPT), and in-circuit test (ICT) are available. Each of these technologies has its own fault coverage and performance characteristics that users must evaluate against their fault spectrum and performance goals before determining their test strategy. The loss of ICT test access adds another dimension of complexity to the problem for many modern PCBAs. To read more about this topic, click here:

http://www.teradyne.com/prods/cbt/products/library/spectr/Printed_Circuit_Europe.pdf

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http://www.teradyne.com/prods/cbt/news/news_pubs.html

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